CLAIMS

1. Composition comprising ethanesulfonic acid or 1-propanesulfonic acid, for use as a medicament.

2. Composition for the use according to claim 1, wherein said ethanesulfonic acid is ethanesulfonic acid 97% and said 1-propanesulfonic acid is 1-propanesulfonic acid 98%.

3. Composition for the use according to claim 1, or 2, further comprising a proton acceptor.

4. Composition for the use according to claim 3, wherein said proton acceptor is selected from the group consisting of: dimethyl sulfoxide, silicon dioxide, tetraethoxysilane, and mixtures thereof.

5. Composition for the use according to any one of claim 1 or 4, prepared in the form of a gel.

6. Composition for the use according to claim 4, or 5, having the following formulation:

Ethanesulfonic acid	70-90% by weight
Dimethyl sulfoxide	5-20% by weight
Silicon dioxide	1-8% by weight
Tetraethoxysilane	0.05-2% by weight

7. Composition for the use according to claim 4, or 5, having the following formulation:

1-propanesulfonic acid	70-90% by weight
Dimethyl sulfoxide	5-20% by weight
Silicon dioxide	1-8% by weight
Tetraethoxysilane	0.05-2% by weight

8. Use of the composition as defined in any one of claims 1 to 7 in the manufacture of a medicament for removing biofilm and necrotic or infected tissues from a skin lesion.

9. Use according to claim 8, wherein said use comprises removing said composition from said skin lesion after a contact time of a few tens of seconds has elapsed.

10. Use according to any one of claims 8 and 9, wherein said skin lesion is a chronic cutaneous ulcer.

11. Use of the composition as defined in any one of claims 1 to 7 in the manufacture of a medicament for the treatment of a chronic cutaneous ulcer.

12. Composition comprising ethanesulfonic acid or 1-propanesulfonic acid, further comprising a proton acceptor.

13. Composition according to claim 12, wherein said ethanesulfonic acid is ethanesulfonic acid 97% and said 1-propanesulfonic acid is 1-propanesulfonic acid 98%.

14. Composition according to claim 12 or 13, wherein said proton acceptor is selected from the group consisting of: dimethyl sulfoxide, silicon dioxide, tetraethoxysilane, and mixtures thereof.

15. Composition according to any one of claims 12 to 14, prepared in the form of a gel.

16. Composition according to claim 14, or 15, having the following formulation:

Ethanesulfonic acid	70-90% by weight
Dimethyl sulfoxide	5-20% by weight
Silicon dioxide	1-8% by weight
Tetraethoxysilane	0.05-2% by weight

17. Composition according to claim 14, or 15, having the following formulation:

1-propanesulfonic acid	70-90% by weight
Dimethyl sulfoxide	5-20% by weight
Silicon dioxide	1-8% by weight
Tetraethoxysilane	0.05-2% by weight